

**AMENDMENTS TO THE TITLE AND ABSTRACT**

**In The Title:**

Please amend the title as follows:

A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND A  
METHOD OF MANUFACTURING THE SAME TO PROVIDE IMPROVED  
ADHESION BETWEEN BONDING PADS AND BALL PORTIONS OF ELECTRICAL  
CONNECTORS

**In The Abstract:**

Please replace the Abstract with the new Abstract attached hereto as Appendix A.

## ABSTRACT

A method is provided to improve adhesion between bonding pads and ball portions of gold wires to improve reliability of a semiconductor device. About 1 wt.% of Pd is contained in gold wires for connection between electrode pads formed on a wiring substrate and electrode pads (exposed areas of a top layer wiring formed mainly of Al) formed on a semiconductor chip. In bonded portions between the electrode and ball portions of the gold wires, an interdiffusion of Au and Al is suppressed to prevent the formation of  $\text{Au}_4\text{Al}$  after POT (Pressure Cooker Test). Thus, a desired bonding strength is obtained even when the pitch of the electrode pads is smaller than 65  $\mu\text{m}$  and the diameter of the ball portion is smaller than 55  $\mu\text{m}$  or the diameter of the wire portion of each gold wire is not larger than 25  $\mu\text{m}$ .

**APPENDIX A**